

Title (en)

LIGHT-UP PREVENTION IN ELECTROSTATIC CHUCKS

Title (de)

ENTZÜNDUNGSSCHUTZ IN ELEKTROSTATISCHEN CHUCKS

Title (fr)

PRÉVENTION D ALLUMAGE DANS DES MANDRINS ÉLECTROSTATIQUES

Publication

EP 2460179 A2 20120606 (EN)

Application

EP 10804865 A 20100629

Priority

- US 51252009 A 20090730
- US 2010040284 W 20100629

Abstract (en)

[origin: US2011024049A1] An electrostatic chuck assembly is provided comprising a ceramic contact layer, a patterned bonding layer, an electrically conductive base plate, and a subterranean arc mitigation layer. The ceramic contact layer and the electrically conductive base plate cooperate to define a plurality of hybrid gas distribution channels formed in a subterranean portion of the electrostatic chuck assembly. Individual ones of the hybrid gas distribution channels comprise surfaces of relatively high electrical conductivity presented by the electrically conductive base plate and relatively low electrical conductivity presented by the ceramic contact layer. The subterranean arc mitigation layer comprises a layer of relatively low electrical conductivity and is formed over the relatively high conductivity surfaces of the hybrid gas distribution channels in the subterranean portion of the electrostatic chuck assembly. Semiconductor wafer processing chambers are also provided.

IPC 8 full level

B23Q 3/15 (2006.01); **C23C 16/458** (2006.01); **H01L 21/683** (2006.01); **H01L 21/687** (2006.01); **H02N 13/00** (2006.01)

CPC (source: EP KR US)

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